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Sommario/riassunto	"A wafer (often from silicon crystals) is a thin slice of semiconducting material, upon which microcircuits are constructed by doping, etching, and deposition of various materials. Generally, they are cut from a semiconductor using a diamond saw, then polished on one or both faces. Wafer slicing is the first post crystal-growth step toward producing a polished wafer for electronic device fabrication in the semiconductor and photovoltaic (PV) industry. Advanced slicing technologies such as wiresawing are nowadays widely used in wafer production because of its ability to cut single crystalline and polycrystalline crystals with large diameter and produce wafers from thick (a few mm) to very thin sizes (300 microns)."--